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INVENTOR-INFORMATION:

NAME

HAMAGUCHI, HIROYUKI

ASSIGNEE-INFORMATION:

NAME

NEC CORP

COUNTRY

N/A

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ABSTRACT:

PURPOSE: To make it possible to use all leads connected to the peripheral part of a semiconductor component as leads for signal use by a method wherein power electrodes and grounding electrode are formed on the central part of the surface of the semiconductor component and a supply of a power supply and the ground is performed through the electrodes.

CONSTITUTION: A semiconductor chip 1 is installed facing the surface of a circuit to its lower side and power electrodes 4 provided closer to the central part of the circuit surface and pads 8 for power electrode use are connected to each other by soldering. Moreover, leads 3 are connected to pads 7 for lead

use provided on the periphery of the circuit surface of the chip 1 by thermocompression bonding. In short, a signal is transmitted in the order of the chip 1 &sim; bump electrodes 2 &sim; the leads 3 &sim; the pads 7 &sim; internal wirings 10. Moreover, a power supply and the ground are connected with the chip &sim; the electrodes 4 &sim; the pads 8 &sim; the wirings 10 and the power supply and the ground can be supplied to the chip 1. Thereby, all the leads can be used as leads for signal use.

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